

**Call for Papers**  
**for a special issue of**  
**IEEE Transactions on Device and Materials Reliability**  
**“Materials, Processing and Reliability of 3D Interconnects”**  
*(Submission deadline has changed from October 31, 2011 to September 30, 2011)*

3D integration has emerged as a potential solution to overcome the wiring limit imposed on chip performance and packaging form factor beyond the 32 nm technology node. The development of 3D interconnects has been established as a focus area in the ITRS roadmaps. While the current effort has been concentrated on the design and processing development, the 3D integration faces serious materials and reliability challenges. The development of the 3D interconnects is at a rapid growth stage where innovative structure, design and processing are being developed at a fast pace. Technical exchange of information and research results can be particularly useful at this time to advance the development of this important technology. We are calling for contribution of technical papers on 3D interconnects for a special issue on materials, processing and reliability of 3D interaction to be published in the Transaction of Devices and Materials Reliability. Some suggested topics of interest include: process integration of 3D interconnects, stress analysis and modeling of 3D structures, thermal management for 3D applications and interfacial adhesion and electromigration of TSV contacts.

Please submit papers by using the website: <http://mc.manuscriptcenter.com/tdmr>  
**BE SURE TO MENTION THE SPECIAL ISSUE WITHIN THE COVER LETTER**

Submission Deadline: **September 30, 2011** Scheduled Publication Date: **March 2012**

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